

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	67680	leadframe (lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:31
L2	1376688	(first second plurality multi mulitple upper lower bottom top) with (substrate carrier board pcb ((Printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L3	20171	(inner distal end tip) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:34
L4	1856	3 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L5	1511	(chip die semiconductor ic (integrated adj circuit) device component electronic) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:37
L6	1481736	(first second plurality multi mulitple upper lower bottom top) with (ceramic alumina substrate carrier board pcb ((Printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L7	1980	3 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L8	1609	(chip die semiconductor ic (integrated adj circuit) device component electronic) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:37

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L5	1511	(chip die semiconductor ic (integrated adj circuit) device component electronic) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:37
L6	1481736	(first second plurality multi mulitple upper lower bottom top) with (ceramic alumina substrate carrier board pcb ((Printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L7	1980	3 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:36
L8	1609	(chip die semiconductor ic (integrated adj circuit) device component electronic) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:38

L9	1132	(distal inner) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:38
L10	187	(offset squirt corrugate corrugation corrugated corrugating emboss embossed embossing) and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:39